

Customer No.: 31561  
Application No.: 10/605,163  
Docket No.: 10230-US-PA

### AMENDMENTS

#### In the Claims:

1. (previously presented) A multi-chip module (MCM) package, comprising:
    - a substrate having an opening therein;
    - a plurality of first bumps;
    - a first chip that has an active surface bonded to and electrically connected with the substrate through the first bumps, the active surface of the first chip facing the opening of the substrate;
    - a plurality of second bumps;
    - at least one second chip disposed in the opening of the substrate and bonded to the active surface of the first chip through the second bumps, the second chip being electrically connected to the first chip through the second bumps; and
    - at least one heat spreader disposed in the opening of the substrate and bonded to the active surface of the first chip, the heat spreader comprising a dummy chip.
  2. (original) The MCM package of claim 1, further comprising a filling material in the opening of the substrate, between the first chip and the second chip and between the first chip and the substrate, the filling material encapsulating the first bumps and the second bumps.
- Claim 3 (canceled)
4. (previously presented) The MCM package of claim 1, wherein the surface of the heat spreader is plated with gold.

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5. (original) The MCM package of claim 1, further comprising a plurality of third bumps for bonding the heat spreader to the active surface of the first chip.

6. (original) The MCM package of claim 1, further comprising a thermally conductive adhesive for bonding the heat spreader to the active surface of the first chip.

7. (previously presented) The MCM package of claim 1, wherein the first chip further comprises a ground contact and the second bumps comprises a ground bump.

8. (original) The MCM package of claim 7, wherein the heat spreader is electrically connected to the ground contact through the ground bump.

Claims 9-25 (canceled)

26. (previously presented) A multi-chip module (MCM) package, comprising:

a substrate having a hole therein;

a plurality of first bumps;

a first chip that has an active surface bonded to and electrically connected with the substrate through the first bumps, the active surface of the first chip facing the hole of the substrate;

a plurality of second bumps;

at least one second chip disposed in the hole of the substrate and bonded to the active surface of the first chip through the second bumps, the second chip being electrically connected to the first chip through the second bumps; and

at least one heat spreader disposed in the hole of the substrate and bonded to the active surface of the first chip, the heat spreader comprising a dummy chip.